4096 x 1-BIT DYNAMIC RAM

Processed to MIL-STD-883, Method 5004, Class B

MKB4027(J)-83/84

FEATURES

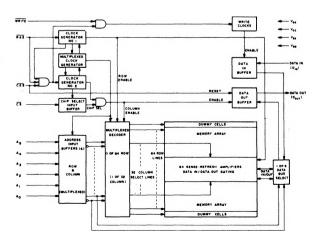
- □ Extended operating temperature range (-55°C \leq T_A \leq +85°C)
- Industry standard 16-pin DIP (MK4096) configuration
- 200ns access time, 375ns cycle (-83)
 250ns access time, 375ns cycle (-84)
- $\square \pm 10\%$ tolerance on all supplies (+12V, \pm 5V)
- Low Power: 467mW active (max) 40mW standby (max)

DESCRIPTION

The MKB4027 is a 4096 word by 1 bit MOS random access memory circuit fabricated with Mostek's Nchannel silicon gate process. This process allows the MKB4027 to be a high performance state-of-the-art memory circuit that is manufacturable in high volume. The MKB4027 employs a single transistor storage cell utilizing a dynamic storage technique and dynamic control circuitry to achieve optimum performance with low power dissipation.

A unique multiplexing and latching technique for the address inputs permits the MKB4027 to be packaged in a standard 16-pin DIP on 0.3 in. centers. This package size provides high system-bit densities and is compatible

FUNCTIONAL DIAGRAM

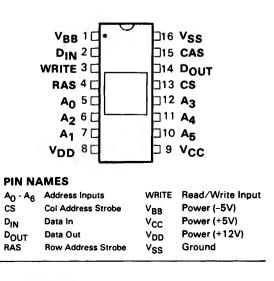


- □ Improved performance with "gated CAS," "RAS only" refresh and page mode capability
- □ All inputs are low capacitance and TTL compatible
- Input latches for addresses, chip select and data in
- Three-state TTL compatible output
- Output data latched and valid into next cycle
- □ Ruggedized for use in severe military environments

with widely available automated testing and insertion equipment.

System oriented features include direct interfacing capability with TTL, only 6 very low capacitance address lines to drive, on-chip address and data registers which eliminates the need for interface registers, input logic levels selected to optimize noise immunity, and two chip select methods to allow the user to determine the appropriate speed/power characteristics of his memory system. The MKB4027 also incorporates several flexible operating modes. In addition to the usual read and write cycles, read-modify write, page-mode, and RAS only refresh cycles are available with the MKB4027. Page-mode timing is very useful in systems requiring Direct Memory Access (DMA) operation.

PIN CONNECTIONS



XII-35

ABSOLUTE MAXIMUM RATINGS*

Voltage on any pin relative to V _{BB}	0.5V to +20V
Voltage on V _{DD} , V _{CC} relative to V _{SS}	
$V_{BB} - V_{SS} (V_{DD} - V_{SS} > 0)$	
Operating Temperature (Ambient)(Ceramic)	
Storage Temperature (Ambient)(Ceramic)	65°C to +150°C
Short Circuit Output Current	50mA
Power Dissipation	1 Watt

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED DC OPERATING CONDITIONS⁴

 $(-55^{\circ}C \le T_{A} \le 85^{\circ}C)$

SYM	PARAMETER	MIN	ТҮР	MAX	UNITS	NOTES
V _{DD}	Supply Voltage	10.8	12.0	13.2	v	2
V _{CC}	Supply Voltage	4.5	5.0	5.5	v	2,3
V _{SS}	Ground	0	0	0	v	2
V _{BB}	Supply Voltage	-4.5	-5.0	-5.5	v	2
VIHC	Logic 1 Voltage, RAS, CAS, WRITE	2.7		7.0	v	2
VIH	Logic 1 Voltage, all inputs except RAS, CAS, WRITE	2.4		7.0	V	2
VIL	Logic O Voltage, all inputs	-1.0	-	.8	v	2

DC ELECTRICAL CHARACTERISTICS⁴

 $(-55^{\circ}C \le T_A \le 85^{\circ}C)^1$ (V_{DD} = 12.0V ± 10%; V_{CC} = 5.0V ± 10%; V_{SS} = 0V; V_{BB} = -5.0V ± 10%)

SYM	PARAMETER	MIN	ТҮР	MAX	UNITS	NOTES
	Avg. V _{DD} Power Supply Current			35	mA	5
IDD2	Standby V _{DD} Power Supply Current			3.0	mA	8
IDD3	Avg. V _{DD} Power Supply Current during "RAS only" cycles			27	mA	
lcc	V _{CC} Power Supply Current				mA	6
IBB	Avg. V _{BB} Power Supply Current			200	μA	
l(L)	Input Leakage Current (any input)			10	μÂ	7
lO(L)	Output Leakage Current			10	μA	8,9
VOH	Output Logic 1 Voltage @ I _{OUT} = -5mA	2.4			V	;
VOL	Output Logic 0 Voltage @ I _{OUT} = 3.2mA			0.4	V	

NOTES:

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 T_A is specified for operation at frequencies to t_{RC}≥t_{RC}(min). Operation at higher cycle rates with reduced ambient temperatures and higher power dissipation is permissible provided that all AC parameters are met.

2. All voltages referenced to VSS.

- Output voltage will swing from V_{SS} to V_{CC} when enabled, with no output load. For purposes of maintaining data in standby mode, V_{CC} may be reduced to V_{SS} without affecting refresh operations or data retention. However, the V_{OH} (min) specification is not guaranteed in this mode.
- Several cycles are required after power-up before proper device operation is achieved. Any 8 cycles which perform refresh are adequate for this purpose.
- Current is proportional to cycle rate. IDD1 (max) is measured at the cycle rate specified by tRC (min). See Figure 1 for IDD1 limits at other cycle rates.

6. I_{CC} depends on output loading. During readout of high level data V_{CC} is connected through a low impedance (135 Ω typ) to Data Out. At all other times I_{CC} consists of leakage currents only.

ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS (4,11,7)

$(-55^{\circ}C \le T_A \le 85^{\circ}C)^1 (V_{DD} =$	$12.0V \pm 10\%$, $V_{CC} = 0V$, $V_{BB} = -5.0V \pm 10\%$)
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		MKB4027-83 MKB4027-84					
SYM	PARAMETER	MIN	MAX	MIN	MAX	UNITS	NOTES
tRC	Random read or write cycle time	375		380		ns	12
tRWC	Read-write cycle time	375	-	395		ns	12
tRMW	Read Modify Write Cycle	405		470		ns	12
tPC	Page mode cycle time	225		285		ns	12
^t RAC	Access time from row address strobe		200		250	ns	13,15
tCAC	Access time from column address strobe		135		165	ns	14,15
tOFF	Output buffer turn-off delay		50		60	ns	
tRP	Row address strobe precharge time	120		120		ns	
tRAS	Row address and strobe pulse width	200	5000	250	5000	ns	
tRSH	Row address strobe hold time	135		165		ns	
^t CAS	Column address strobe pulse width	135		165		ns	
^t CSH	CAS hold time	200		250		ns	
^t RCD	Row to column strobe delay	25	65	35	85	ns	16
^t ASR	Row address set-up time	0		0		ns	
^t RAH	Row address hold time	25		35		ns	
tASC	Column address set-up time	0		0		ns	
^t CAH	Column address hold-time	55		75		ns	
^t AR	Column address hold time referenced to RAS	120		160		ns	
tcsc	Chip select set-up time	0		0		ns	
^t CH	Chip select hold time	55		75		ns	
^t CHR	Chip select hold time referenced to RAS	120		160		ns	
t _T	Transition time (rise and fall)	3	50	3	50	ns	17
t _{RC} S	Read command set-up time	0		0		ns	
^t RCH	Read command hold time	0		0		ns	
tWCH	Write command hold time	55		75		ns	
tWCR	Write command hold time referenced to RAS	120		160		ns	
twp	Write command pulse width	55		75		ns	
^t RWL	Write command to row strobe lead time	70		85		ns	
tCWL	Write command to column strobe lead time	70		85		ns	
tDS	Data in set-up time	0		0		ns	18

ELECTRICAL CHARACTERISTICS (Continued)

SYM	PARAMETER	МКВ4	мкв4027-84				
		MIN	MAX	MIN	MAX	UNITS	NOTES
^t DH	Data in hold time	55		75		ns	18
^t DHR	Data in hold time referenced to RAS	120		160		ns	
tCRP	Column to row strobe precharge time	0		0		ns	
tCP	Column precharge time	80		110	1	ns	
tRFSH	Refresh Period		2		2	ms	
twcs	Write command set-up time	0		0			19
tCWD	CAS to WRITE delay	80		80	_	ns	19
tRWD	RAS to WRITE delay	145		175		ns	19
^t DOH	Data out hold time	5		5		μs	

NOTES (Continued)

- All device pins at 0 volts except V_{BB} which is at -5 volts and the pin under test which is at -10 volts.
- Output logic is disabled (high-impedance) and RAS and CAS are both at a logic 1. Transient stabilization is required prior to measurement of this parameter.
- 9. $0V \le V_{OUT} \le -10V$
- 10. Effective capacitance is calculated from the equation: $C = \frac{\Delta O}{V} \text{ with } \Delta V = 3 \text{ Volts}$
- 11. AC measurements assume t₁ = 5ns.
- 12. The specification for t_{RC} (min) and t_{RWC} (min) are used only to indicate cycle time at which proper operation over the full temperature range $(-55^{\circ}C \le T_{A} \le 85^{\circ}C)$ is assured. See Figure 2 for derating curve.
- 13. Assumes that $t_{RCD} \leq t_{RCD}$ (max)
- 14. Assumes that $t_{RCD} \ge t_{RCD}$ (max)

AC ELECTRICAL CHARACTERISTICS

- 15. Measured with a load circuit equivalent to 2 TTL loads and 100pF.
- Operation within the t_{RAC} (max) limit insures that t_{RCD} (max) is specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
- 17. V_{IHC} (min) or V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IHC} or V_{IH} and V_{IL} .
- 18. These parameters are referenced to CAS leading edge in random write cycles to WRITE leading edge in delayed write or read-modify-write cycles.
- 19. tWCS. tCWD, and tRWD are restrictive operating parameters in a read/write or read/write vccle only. If tWCS ≥ tWCS (min), the cycle is an early write cycle and the Data Dut will contain the data written into the selected cell. If tCWD ≥ tCWD (min) and tRWD ≥ tRWD (min), the cycle is a read-write cycle and Data Dut will contain data read from the selected cell. If neither of the above sets of conditions is satisfied, the condition of Data Out (at access time) is indetermined.

 $(-55^{\circ}C \le T_{A} \le 85^{\circ}C)^{1}$ (V_{DD} = 12.0V ± 10%, V_{CC} = 5V ± 10%, V_{SS} = 0V, V_{BB} = -5.0V ± 10%)

SYM	PARAMETER	ТҮР	MAX	UNITS	NOTES
C _{I1}	Input Capacitance (A _O - A ₅), D _{IN} , CS	4	5	pF	10
C ₁₂	Input Capacitance RAS, CAS, WRITE	8	10	pF	10
с _О	Output Capacitance (D _{OUT})	5	7	pF	8,10

SUPPLEMENTAL DATA SHEET TO BE USED IN CONJUNCTION WITH MOSTEK MK4027(J)-1/2/3 and MK4027(J)-4 DATA SHEETS